



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of: **Miwa KOZAWA et al.**

Group Art Unit: **1752**

Application Number: **10/629,806**

Examiner: **Sin J. Lee**

Filed: **July 30, 2003**

Confirmation No.: **9494**

For: **RESIST PATTERN THICKENING MATERIAL, PROCESS FOR  
FORMING RESIST PATTERN, AND PROCESS FOR  
MANUFACTURING SEMICONDUCTOR DEVICE**

Attorney Docket Number: **030923**

Customer Number: **38834**

**AMENDMENT AFTER FINAL**

**MAILSTOP: AF**

Commissioner for Patents

P. O. Box 1450

Alexandria, VA 22313-1450

April 11, 2006

Sir:

In response to the Office Action dated December 13, 2005, the response due date extended to April 13, 2006 by a 1-month Extension of Time, please amend the above-identified application as follows:

**Amendments to the Claims** begin at page 2 of this paper.

**Remarks** begin on page 8 of this paper.

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S.J.L.

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